

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of

H. ARAI et al

Serial No.

Filed: March 7, 2002

For: A SEMICONDUCTOR DEVICE AND METHOD OF
MANUFACTURING THE SAME

AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

Sir:

Prior to examination, please amend the above-identified application as follows.

IN THE ABSTRACT

Page 76 and 77, "Abstract of the Disclosure" section, delete this section in its entirety and replace with:

A semiconductor chip has a quadrangle main surface, a wiring substrate, and a resin seal member for sealing the semiconductor chip, in which the resin seal member has a quadrangle main surface which confronts the main surface of the semiconductor chip. A gate cut trace portion is formed on a side face extending along a first side of the main surface of the resin seal member. A sectional area of an area between the main surface of the wiring substrate and the main surface of the resin seal member at a position outside a side face of the semiconductor chip is smaller than a sectional area of an

area between the main surface of the semiconductor chip and the main surface of the resin seal member.

IN THE CLAIMS

Rewrite claim 7 and add new claim 8 as follows:

7. (Amended) A semiconductor device according to claim 4, wherein the main surface of the semiconductor chip is formed in a rectangular shape in which the first and second sides of the main surface of the semiconductor chip are a long side and a short side, respectively.

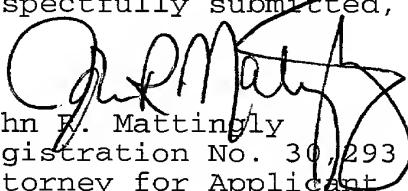
8. (New) A semiconductor device according to claim 4, wherein the main surface of the semiconductor chip is formed in a rectangular shape in which the first and second sides of the main surface of the semiconductor chip are a short side and a long side, respectively.

REMARKS

Claim 7 has been amended to correct an inadvertent error, and claim 8 was unintentionally omitted from the application and has been added.

Examination is requested.

Respectfully submitted,


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MARKED UP VERSION OF REPLACED SECTION OF THE SPECIFICATION

Pages 76 and 77, "Abstract of the Disclosure" section,
the marked up version of this section is:

[A semiconductor device comprising] A semiconductor chip
[having] has a quadrangle main surface, a wiring substrate
[with the semiconductor chip disposed on a main surface
thereof], and a resin seal member for sealing the
semiconductor chip, in which the resin seal member [having]
has a quadrangle main surface which confronts the main surface
of the semiconductor chip[,]. [and a] A gate cut trace portion
is formed on a side face extending along a first side of the
main surface of the resin seal member. [wherein the first side
of the main surface of the resin seal member extends along a
first side of the main surface of the semiconductor chip, the
main surface of the resin seal member has a second side
intersecting the first side thereof, the second side of the
main surface of the resin seal member extending along a second
side of the main surface of the semiconductor chip which
second side intersects the first side of the chip main
surface, and in a section orthogonal to the second side of
the main surface of the semiconductor chip, a] A sectional
area of an area between the main surface of the wiring
substrate and the main surface of the resin seal member at a
position outside a side face of the semiconductor chip is
smaller than a sectional area of an area between the main

surface of the semiconductor chip and the main surface of the resin seal member. [It is possible to suppress the occurrence of void.]

MARKED UP VERSION OF REWRITTEN CLAIMS

7. (Amended) A semiconductor device according to claim 4, wherein the main surface of the semiconductor chip is formed in a rectangular shape in which the first and second sides of the main surface of the semiconductor chip are a [short] long side and a [long] short side, respectively.